

# B6605AFHBF2100TN ELEPEAK 5VDC 66x60x5mm Centrifugal Blower Datasheet



**Brand:** ELEPEAK

**SKU:** [994133174084](#)

**Category:** Axial & Centrifugal Fans

**Price:** **\$20.99**

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Product Page:

<https://www.equipspares.com/product/b6605afhbf2100tn-elepeak-5vdc-66x60x5mm-centrifugal-blower>

## Product Description

ELEPEAK B6605AFHBF2100TN is a 5VDC 66x60x5mm Centrifugal Blower optimized for ultra-thin laptop thermal management and high-density heat dissipation. Engineered with a precision DC motor and advanced fluid dynamic bearing architecture, this unit minimizes thermal impedance while maintaining structural rigidity in constrained chassis environments. The aerodynamic impeller design is specifically tuned for the Lenovo ThinkBook 13X G2 IAP, ensuring efficient heat extraction from CPU/GPU heat pipes. Operating at 0.5A with a rated power of 2.5W, it provides the necessary static pressure to overcome internal system resistance. This replacement fan integrates seamlessly with 4-pin PWM headers for dynamic speed modulation and acoustic optimization.

Model Number: B6605AFHBF2100TN

Brand: ELEPEAK

Product Type: Centrifugal Blower

Rated Voltage: 5VDC

Voltage Range: 4.5 - 5.5 VDC

Rated Current: 0.5A

Power: 2.5W

Rated Speed: 4800 RPM

Bearing Type: Fluid Dynamic Bearing

Max. Air Flow: 4.20 CFM (7.14 m<sup>3</sup>/h / 0.12 m<sup>3</sup>/min)

Max. Static Pressure: 12.50 mmH<sub>2</sub>O (122.58 Pa / 0.49 inH<sub>2</sub>O)

Dimensions: 66mm x 60mm x 5mm

Weight: 25g

Life Expectancy: 40,000 hours at 40C

Speed Control: PWM (4-Wire)

Termination: 4-Pin Connector

Housing Material: UL94V-0 Plastic / Aluminum Plate

Operating Temperature: -10C to +70C

Part Number Compatibility: 5F10S14019

Protection Features: Locked Rotor Protection, Auto Restart

B6605AFHBF2100TN Applications

1. Ultra-thin Laptop Thermal Modules: Specifically engineered as a replacement fan for Lenovo ThinkBook 13X G2 IAP (5F10S14019) to restore factory-spec cooling efficiency in sub-15mm chassis.
2. High-Density Mobile Computing: Ideal for overcoming high system impedance in compact heat pipe assemblies where low-profile vertical exhaust is required.

## Supplemental Images

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